Title (en)

FLOORING COMPOSED OF CERAMIC TILES

Publication

EP 0239041 B1 19920603 (DE)

Application

EP 87104187 A 19870321

Priority

DE 3610565 A 19860327

Abstract (en)

[origin: EP0239041A2] A flooring composed of ceramic tiles traditionally has a bed of mortar as an adhesive layer which levels out the unevennesses of the substructure. This layer is replaced by rubber underlays (13) which are firmly attached in the factory to the individual tiles (12) and rest loosely on the substructure (2-4); the covering elements (10) thus formed in each case from a tile (12) and its underlay (13) are laid with vertical movability of the tiles (12) relative to one another at the joints (11). Cavities (15) are formed on the underside of the underlays (13), preferably by embossing (14). The tiles are held immovably on the substructure even without bonding due to their soft underlays. The unevennesses of the substructure are levelled out on loading by the elasticity of the underlay in each case. The vertical moveability of the tiles relative to one another concentrates the support of the tile on the underlay, i.e. prevents the introduction of reactive forces from the edge and thus keeps the bending moment confined to the tiles. Consequently, the laying of the covering elements takes place simply by laying on the substructure. The water runs through the joints and drains off under the covering elements in the cavities (15). <IMAGE>

IPC 1-7

E04D 11/00; E04F 15/08

IPC 8 full level

E04D 11/00 (2006.01); **E04F 15/08** (2006.01)

CPC (source: EP)

E04F 15/02183 (2013.01); **E04F 15/087** (2013.01)

Cited by

DE29805940U1; CN106703411A; NL1024921C2; EP1020589A3; DE29805942U1; ES2157788A1; DE102013018198A1; EP2374855A3; EP1609927A3; AU2008230828B2; US9691240B2; WO2005058568A1; EP1609927A2; US9988760B2

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